

# **DEVICE AND METHOD FOR ENCAPSULATING WITH ENCAPSULATING MATERIAL AND ELECTRONIC COMPONENT FIXED ON A CARRIER**

## **ABSTRACT OF THE DISCLOSURE**

The invention relates to a device for encapsulating with encapsulating material an electronic component, in particular a semiconductor, fixed on a carrier, comprising: two co-acting mould parts which are displaceable relative to each other between an encapsulating position, in which the mould parts, when closing onto the carrier, occupy a position for defining at least one mould cavity, and an opened position in which the mould parts are situated at a greater distance from each other than in the encapsulating position, and feed means for encapsulating material connecting onto the mould cavity. The invention also relates to a method for encapsulating with encapsulating material an electronic component fixed on a carrier.